



TESSERA 3.3-018

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re Patent Application of  
KHANDROS et al.

Serial No. 08/030,194

Filed: April 28, 1993

For: SEMICONDUCTOR CHIP ASSEMBLIES,  
METHODS OF MAKING SAME AND  
COMPONENTS FOR SAME

Group Art Unit: 2503

Examiner: S. Clark

Dated: June 26, 1995

Assistant Commissioner For Patents  
Washington, D.C. 20231

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JUL 27 1995

GROUP 2500

AMENDMENT AND RESPONSE

Sir:

Please amend the above-identified application as follows:

In the Specification:

In the cross-reference to related applications at page 1, line 3, after  
"September 24, 1991" insert --now U.S. Pat. No. 5,347,159.--

In the Claims:

Amend Claims 1-6 as follows:

1. A semiconductor <sup>assembly comprising</sup> ~~chip comprising~~ assembly of the type  
including] a semiconductor chip having a plurality of surfaces and having contacts  
on at least one of said surfaces and a flexible sheetlike element having terminals  
thereon, and flexible leads electrically [connected] connecting said terminals to said  
contacts, [characterized in that] wherein said sheetlike element and at least some of  
said terminals overlie one said surface of said chip and said sheetlike element bears  
upon such surface of said chip, said terminals are movable with respect to said chip  
and said contacts; said flexible leads and said flexible sheetlike element being  
adapted to deform to accommodate movement of said terminals with respect to said

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MARCUS J. MILLET

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